

**Amendments to the Claims:**

Following is a complete listing of the claims pending in the application, as amended:

1. – 4. (Cancelled)

5. (Previously presented) An image sensor comprising:

a plurality of pixels formed in a semiconductor substrate, each pixel including a

light sensitive element;

a micro-lens over each of said light sensitive elements; and

a trench structure surrounding each of said micro-lenss, wherein said trench structure has a depth on the order of 0.2 microns.

6. - 11 (Cancelled)

12. (Previously presented) A pixel of an image sensor comprising:

a light sensitive element formed in a semiconductor substrate;

a micro-lens over said light sensitive element; and

a trench structure surrounding said micro-lens, wherein said trench structure has a depth on the order of 0.2 microns.

13 – 19. (Cancelled)